



## Product Change Notification: BLAS-27GJUK085

---

**Date:**

06-Jun-2025

**Product Category:**

32-Bit Microcontrollers

**Notification Subject:**

CCB 7046 Final Notice: Qualification of ATP7 as an additional assembly site for selected ATSAM4S16C, ATSAM4S2C, ATSAM4S4C, ATSAM4S8C, ATSAM4SA16C, ATSAM4SD16C and ATSAM4SD32C device families available in 100L TFBGA (9x9x1.2mm) package.

**Affected CPNs:**

[BLAS-27GJUK085\\_Affected\\_CPN\\_06062025.pdf](#)

[BLAS-27GJUK085\\_Affected\\_CPN\\_06062025.csv](#)

**PCN Status:** Final Notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:** Qualification of ATP7 as an additional assembly site for selected ATSAM4S16C, ATSAM4S2C, ATSAM4S4C, ATSAM4S8C, ATSAM4SA16C, ATSAM4SD16C and ATSAM4SD32C device families available in 100L TFBGA (9x9x1.2mm) package.

**Pre and Post Summary Changes:**

	Pre Change	Post Change	
Assembly Site	ATX Semiconductor (Shanghai) Co. Ltd (ASSH)	ATX Semiconductor (Shanghai) Co. Ltd (ASSH)	Amkor Technology Philippines (P3/P4), INC. (ATP7)

Substrate Core Material	CCL-HL832NX	CCL-HL832NX	HL832NXA
Substrate Core Thickness	100±30 UM	100±30 UM	100 UM
Substrate SM Material	AUS308	AUS308	AUS308
Substrate SM Thickness	30+/-15 UM	30+/-15 UM	30+/-10 UM
Wire Material	CuPd	CuPd	CuPdAu
Die Attach Material	2100AS	2100AS	2300
Molding Compound Material	KE-G1250LKDS	KE-G1250LKDS	G770FE
Solder Ball Material	SAC105	SAC105	SAC105

**Impacts to Datasheet:** None

**Change Impact:** None

**Reason for Change:** To improve on-time delivery performance by qualifying ATP7 as an additional assembly site.

**Change Implementation Status:** In Progress

**Estimated First Ship Date:** 30 June 2025 (date code: 2527)

**Note Below EFSD:** Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Timetable Summary:**

	July 2024					>	June 2025				
Work Week	27	28	29	30	31		23	24	25	26	27
Initial PCN Issue Date		x									
Qual Report Availability							x				

<b>Final PCN Issue Date</b>							X				
<b>Estimated Implementation Date</b>											X

**Method to Identify Change:** Traceability Code

**Qualification Report:** Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:**

July 08, 2024: Issued initial notification.

July 11, 2024: Re-issued initial notification. Corrected PCN number.

June 06, 2025: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on June 30, 2025.

**Note:** The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

**Attachments:**

**[PCN\\_BLAS-27GJUK085\\_Qual Report.pdf](#)**

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

**Terms and Conditions:**

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.